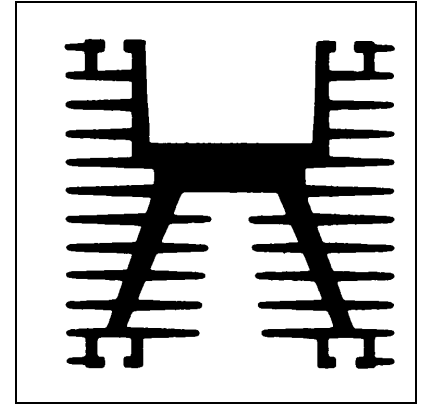


Heatsinks

P 1



Features

- Intended for discrete components and bridge rectifiers
- Available in various lengths
- Several devices can be mounted on a single heatsink
- Mounting channels are provided for additional accessories

Standard lengths ¹⁾	R_{thha} ²⁾ natural cooling °C/W	R_{thha} ³⁾ forced air cooling °C/W	w kg
P 1/75 - M 8 P 1/75 - M12	1,0 (50 W) 0,85 (70 W)	0,45 0,33	0,82
P 1/120 - M 8 P 1/120 - M12	0,75 (100 W) 0,60 (120 W)	0,40 0,28	1,3
P 1/200 - M16 x 1,5 P 1/200 - M24 x 1,5	0,43 (150 W) 0,40 (200 W)	0,17 0,15	2,2
P 1/120 - 45 mm P 1/120 - 49 mm ⁴⁾ P 1/120 - 49 mm ⁵⁾ P 1/120 - 60 mm	0,70 (70 W) 0,70 (70 W) 0,60 (100 W) 0,60 (100 W)	0,25 0,25 0,20 0,21	1,3
P 1/200 - 49 mm ⁵⁾ P 1/200 - 60 mm	0,47 (130 W) 0,47 (130 W)	0,17 0,18	2,2

¹⁾ Non standard lengths available on request

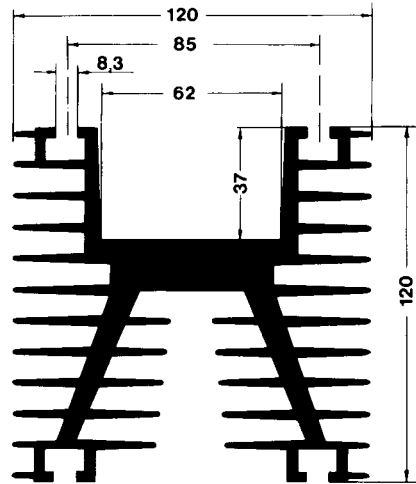
²⁾ At the given power dissipation per semiconductor component

³⁾ With fan type

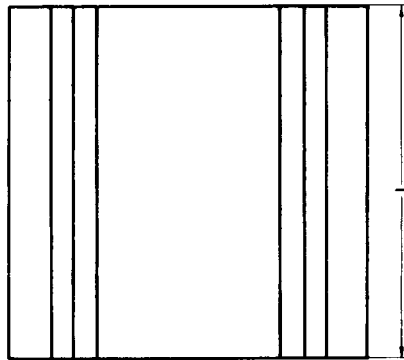
⁴⁾ SEMIPONT 1

⁵⁾ SEMIPONT 2

P1

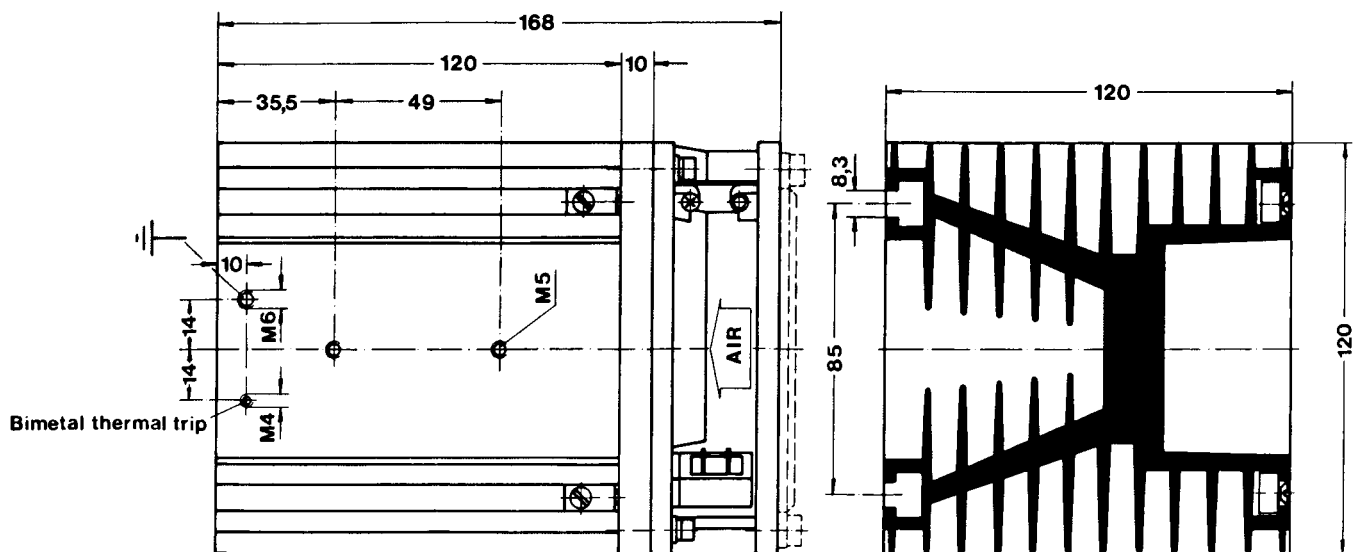


$$\frac{w}{l} = 11,3 \frac{\text{kg}}{\text{m}}$$



P 1/120 : l = 120 mm
P 1/200 : l = 200 mm

Example: P 1/120 F for SEMIPONTS



Dimensions in mm

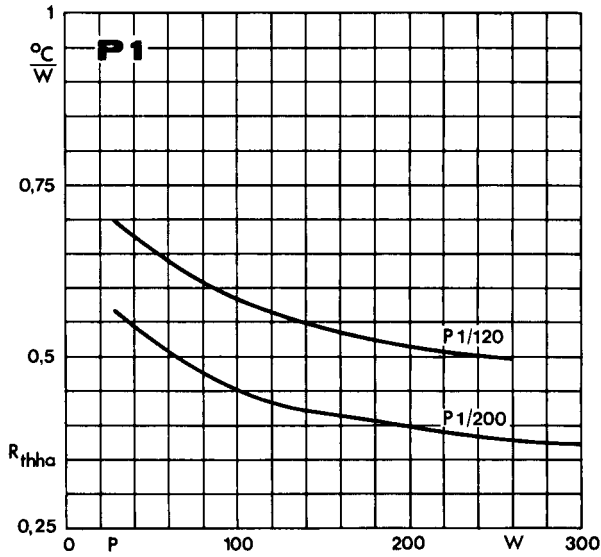


Fig. 1 Thermal resistance vs. dissipated power

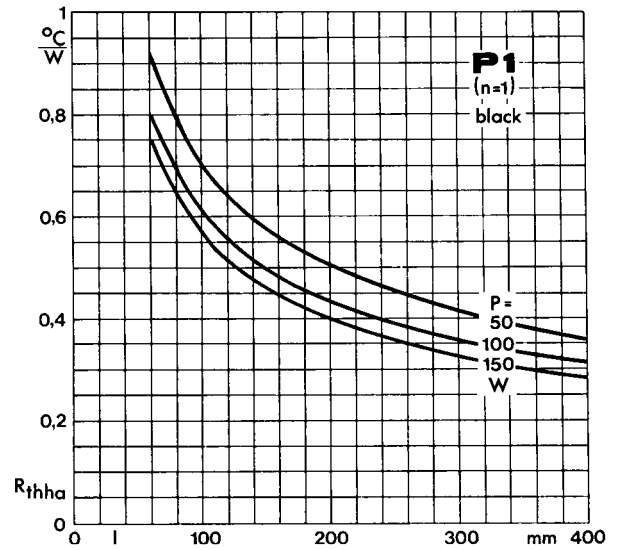


Fig. 2 a Thermal resistance per component vs. length

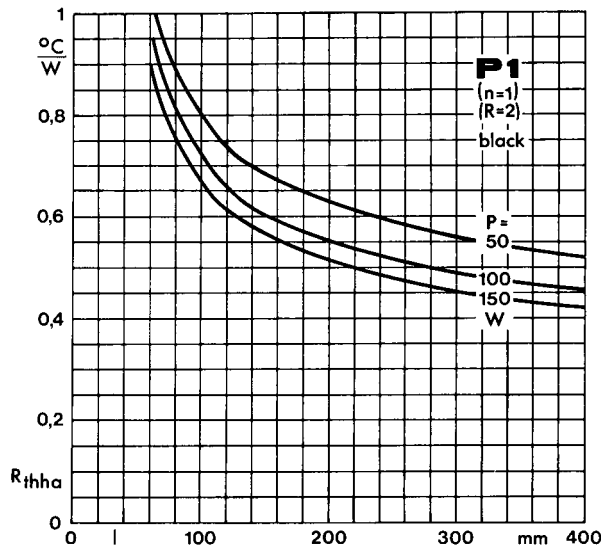


Fig. 2 b Thermal resistance per component vs. length

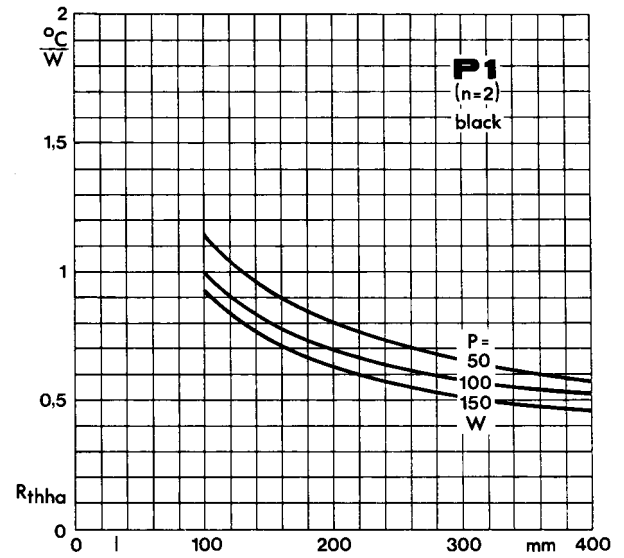


Fig. 2 c Thermal resistance per component vs. length

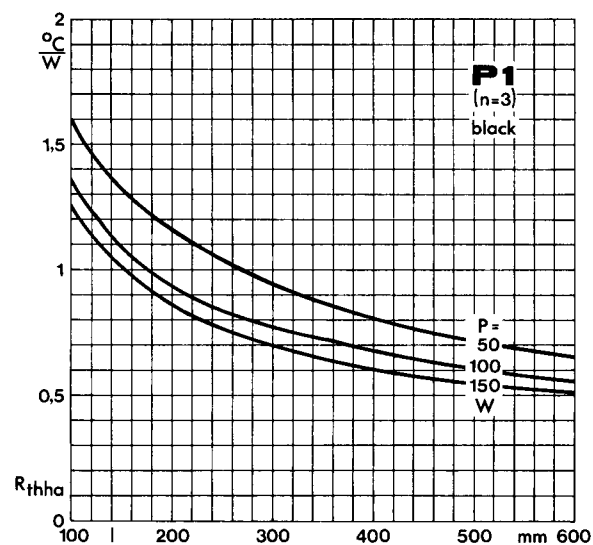


Fig. 2 d Thermal resistance per component vs. length

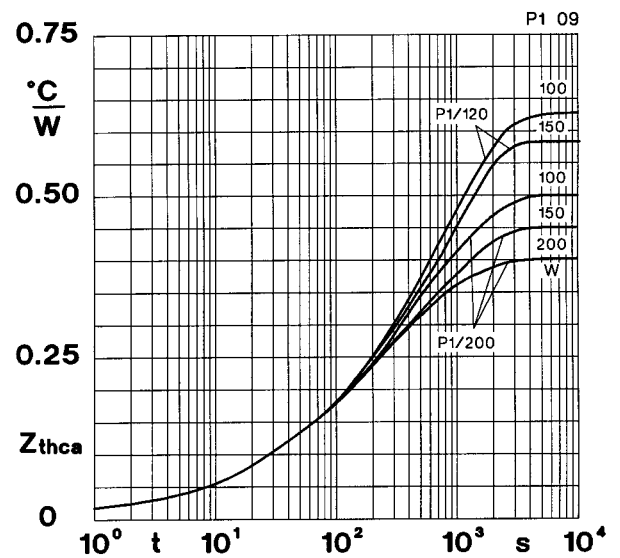


Fig. 9 Transient thermal impedance vs. time